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ABSTRACT OF THE DISCLOSURE

5 Provided is an electrostatic protective device which is highly effective in
protecting relatively vulnerable devices such as IC's and LSI's from electrostatic
damages, and a method for fabricating an electrostatic protective device which
can simplify the structure as compared with the conventional devices sealed in a
glass container, and can reduce the size and cost of the device. The chip type
electrostatic protective device comprises an inner insulating layer made of
10 organic resin material and provided with a plurality of holes for defining air gaps,
a pair of outer insulating layers placed on both sides of the inner insulating layer,
and circuit segments defining a discharge gap in each of the air gaps. Holes for
interconnection are formed in the laminated assembly, and the interior of each of
the holes is turned electroconductive. The assembly is then cut apart into
15 individual chip type electrostatic protective devices by cutting through each of
the holes for interconnection so as to define terminals for interconnection.

Fig 1(k)

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